



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2021-05-31
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
HDMIULC6-4SC6	CDWB*5XWSOIS	A	9992	2021-05-31
	Amount	UoM	Unit type	ST ECOPACK Grade
	14	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	CD00367061	

Package Designator	Size	Nbr of instances	Shape	
DSO	2.90,1.63,1.18	6	gull wing	
Comment	SOT 23 - 6L. MDF valid for CPs: DVIULC6-4SC6,HDMIULC6-4SC6			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 18th December 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.08	leadframe	5429

QueryList : REACH-19th January 2021				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Gold,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

Material Composition Declaration :						Mfr Item Name	CDWB*5XWSOIS					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.006	mg	supplier	die	Silicon(Si)	7440-21-3		0.953	mg	947316	68073
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.003	mg	2982	214
				supplier	metallisation	Copper(Cu)	7440-50-8		0.022	mg	21869	1571
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.001	mg	994	71
				supplier	passivation	Silicon oxide	7631-86-9		0.027	mg	26839	1929
Leadframe	M-004 Copper and its alloys	6.765	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8		6.518	mg	963488	465571
				supplier	alloy & coating	Nickel(Ni)	7440-02-0		0.076	mg	11234	5429
				supplier	alloy & coating	Iron(Fe)	7439-89-6		0.154	mg	22764	11000
				supplier	alloy & coating	Phosphorus metal	7723-14-0		0.002	mg	296	143
				supplier	alloy & coating	Zinc(Zn)	7440-66-6		0.008	mg	1183	571
				supplier	alloy & coating	Palladium(Pd)	7440-05-3		0.005	mg	739	357
				supplier	alloy & coating	Gold(Au)	7440-57-5		0.002	mg	296	143
				supplier	alloy & coating	Copper(Cu)	7440-50-8		0.002	mg	296	143
Die attach		0.054	mg	supplier	glue	Epoxyde bisphenol A resin	25068-38-6		0.005	mg	92592	357
				supplier	glue	Silica vitreous	60676-86-0		0.004	mg	74074	286
				supplier	glue	Ethoxyethoxy-ethyl acetate	112-15-2		0.012	mg	222222	857
				supplier	glue	Aluminium oxide	1344-28-1		0.023	mg	425926	1643
				supplier	glue	Bisphenol A diglycidyl ether polymer	25036-25-3		0.009	mg	166667	643
				supplier	glue	Diaminodiphenylsulfone	proprietary		0.001	mg	18519	71
Bonding wires	M-004 Copper and its alloys	0.160	mg	supplier	wire	Copper (Cu)	7440-50-8		0.157	mg	981250	11214
				supplier	wire	Palladium (Pd)	7440-05-3		0.003	mg	18750	214
Encapsulation	M-011 Other inorganic materials	6.015	mg	supplier	mold compound	Silica, vitreous	60676-86-0		5.132	mg	853201	366571
				supplier	mold compound	phenolic resin	Proprietary		0.210	mg	34913	15000
				supplier	mold compound	epoxy resin	Proprietary		0.240	mg	39900	17143
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.121	mg	20116	8643
				supplier	mold compound	carbon black	1333-86-4		0.012	mg	1995	857
				supplier	mold compound	Zinc hydroxide	20427-58-1		0.060	mg	9975	4286
				supplier	mold compound	Magnesium hydroxide	1309-42-8		0.240	mg	39900	17143